

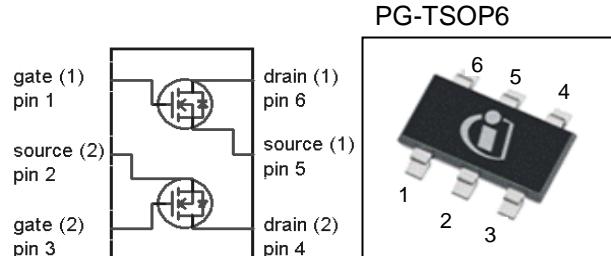
OptiMOS®2 Small-Signal-Transistor

Features

- Dual N-channel
- Enhancement mode
- Super Logic level (2.5V rated)
- Avalanche rated
- Qualified according to AEC Q101
- Pb-free lead plating; RoHS compliant
- Halogen free according to IEC61249-2-21

Product Summary

V_{DS}	20	V
$R_{DS(on),max}$	$V_{GS}=4.5\text{ V}$	50
	$V_{GS}=2.5\text{ V}$	85
I_D	2.5	A



Halogen-Free

Type	Package	Tape and Reel Information	Marking	Lead Free	Packing
BSL205N	PG-TSOP6	H6327: 3000 pcs/ reel	sPK	Yes	Non dry

Maximum ratings, at $T_j=25\text{ }^\circ\text{C}$, unless otherwise specified

Parameter ⁽¹⁾	Symbol	Conditions	Value	Unit
Continuous drain current	I_D	$T_A=25\text{ }^\circ\text{C}$	2.5	A
		$T_A=70\text{ }^\circ\text{C}$	2.0	
Pulsed drain current	$I_{D,pulse}$	$T_A=25\text{ }^\circ\text{C}$	10	
Avalanche energy, single pulse	E_{AS}	$I_D=2.5\text{ A}, R_{GS}=25\text{ }\Omega$	10.8	mJ
Reverse diode dv/dt	dv/dt	$I_D=2.5\text{ A}, V_{DS}=16\text{ V}, di/dt=200\text{ A}/\mu\text{s}, T_{j,max}=150\text{ }^\circ\text{C}$	6	kV/ μs
Gate source voltage	V_{GS}		± 12	V
Power dissipation ⁽³⁾	P_{tot}	$T_A=25\text{ }^\circ\text{C}$	0.5	W
Operating and storage temperature	T_j, T_{stg}		-55 ... 150	$^\circ\text{C}$
ESD Class		JESD22-A114 -HBM	class 0 (<250V)	
Soldering Temperature			260 $^\circ\text{C}$	
IEC climatic category; DIN IEC 68-1			55/150/56	

⁽¹⁾ Remark: one of both transistors in operation.

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

Thermal characteristics

Thermal resistance, junction - ambient	R_{thJA}	minimal footprint ⁽²⁾	-	-	250	K/W
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Electrical characteristics, at $T_j=25$ °C, unless otherwise specified

Static characteristics

Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0$ V, $I_D=250$ μ A	20	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$, $I_D=11$ μ A	0.6	0.95	1.2	
Drain-source leakage current	I_{DSS}	$V_{DS}=20$ V, $V_{GS}=0$ V, $T_j=25$ °C	-	-	1	μ A
		$V_{DS}=20$ V, $V_{GS}=0$ V, $T_j=150$ °C	-	-	100	
Gate-source leakage current	I_{GSS}	$V_{GS}=12$ V, $V_{DS}=0$ V	-	-	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=2.5$ V, $I_D=1.95$ A	-	62	85	mΩ
		$V_{GS}=4.5$ V, $I_D=2.5$ A	-	39	50	
Transconductance	g_{fs}	$ V_{DS} >2 I_D R_{DS(on)max}$, $I_D=2$ A	-	8.6	-	s

⁽²⁾ Performed on 40mm² FR4 PCB. The traces are 1mm wide, 70 μ m thick and 20mkm long; they are present on both sides of the PCB.

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

Dynamic characteristics

Input capacitance	C_{iss}	$V_{GS}=0 \text{ V}, V_{DS}=10 \text{ V}, f=1 \text{ MHz}$	-	315	419	pF
Output capacitance	C_{oss}		-	114	152	
Reverse transfer capacitance	C_{rss}		-	16	24	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=10 \text{ V}, V_{GS}=4.5 \text{ V}, I_D=2.5 \text{ A}, R_{G,ext}=6 \Omega$	-	5.8	-	ns
Rise time	t_r		-	2.9	-	
Turn-off delay time	$t_{d(off)}$		-	11.0	-	
Fall time	t_f		-	2.4	-	

Gate Charge Characteristics

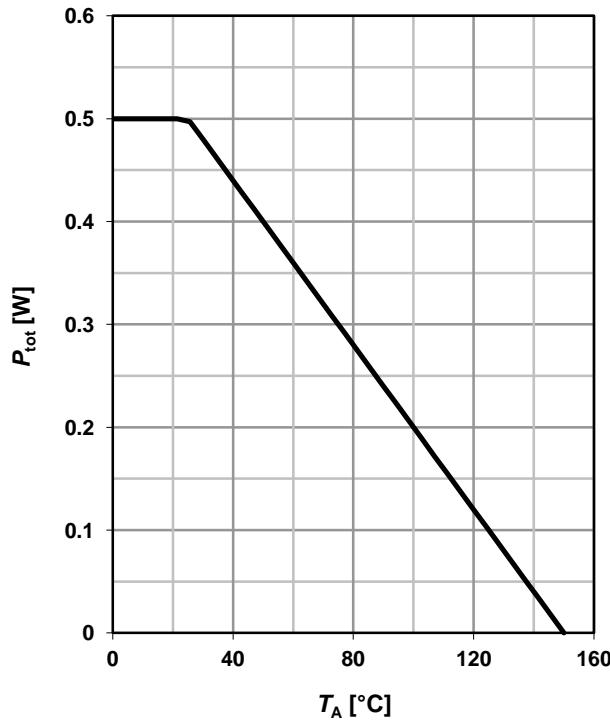
Gate to source charge	Q_{gs}	$V_{DD}=10 \text{ V}, I_D=2.5 \text{ A}, V_{GS}=0 \text{ to } 4.5 \text{ V}$	-	0.65	0.86	nC
Gate to drain charge	Q_{gd}		-	0.5	0.7	
Gate charge total	Q_g		-	2.1	3.2	
Gate plateau voltage	$V_{plateau}$		-	2	-	V

Reverse Diode

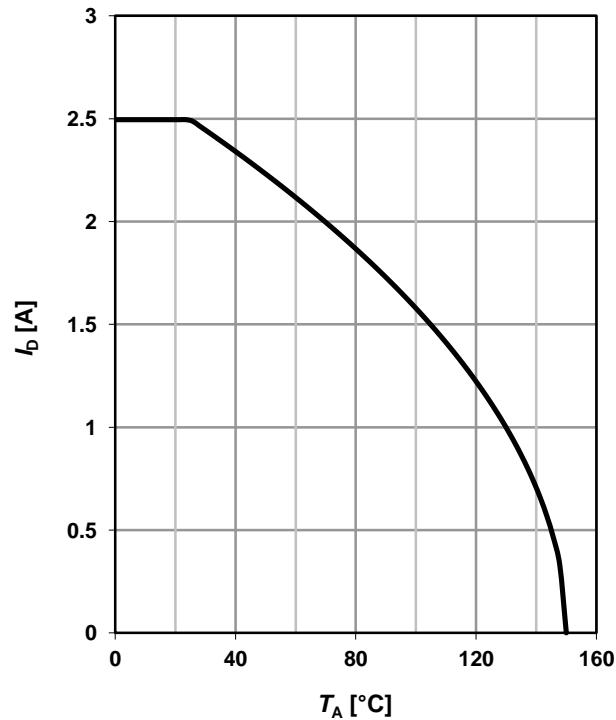
Diode continuous forward current	I_s	$T_A=25 \text{ }^\circ\text{C}$	-	-	0.5	A
Diode pulse current	$I_{s,pulse}$		-	-	10	
Diode forward voltage	V_{SD}	$V_{GS}=0 \text{ V}, I_F=2.5 \text{ A}, T_j=25 \text{ }^\circ\text{C}$	-	0.8	1.1	V
Reverse recovery time	t_{rr}	$V_R=10 \text{ V}, I_F=2.5 \text{ A}, di_F/dt=100 \text{ A}/\mu\text{s}$	-	10	-	ns
Reverse recovery charge	Q_{rr}		-	2.2	-	nC

1 Power dissipation

$$P_{\text{tot}} = f(T_A)$$

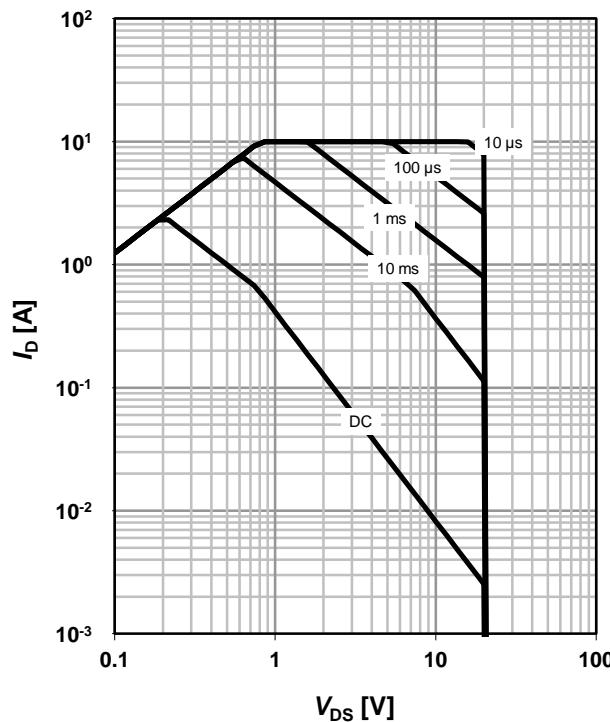

2 Drain current

$$I_D = f(T_A); V_{GS} \geq 4.5 \text{ V}$$


3 Safe operating area

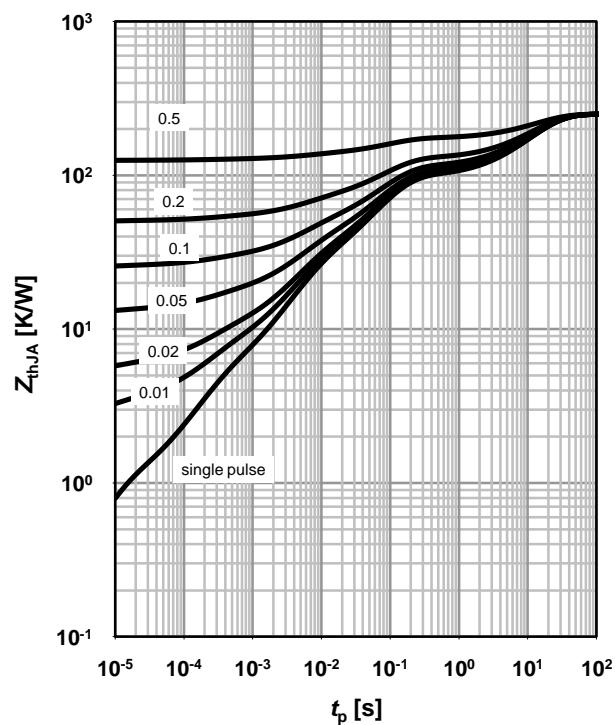
$$I_D = f(V_{DS}); T_A = 25 \text{ °C}; D = 0$$

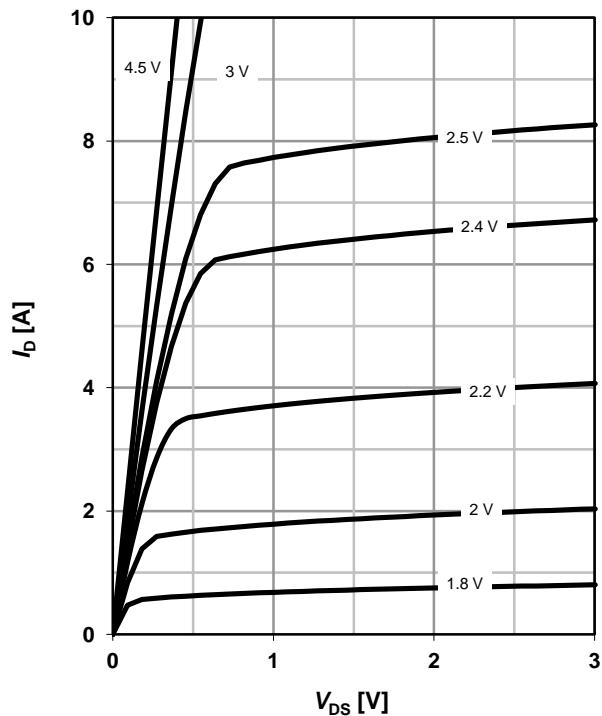
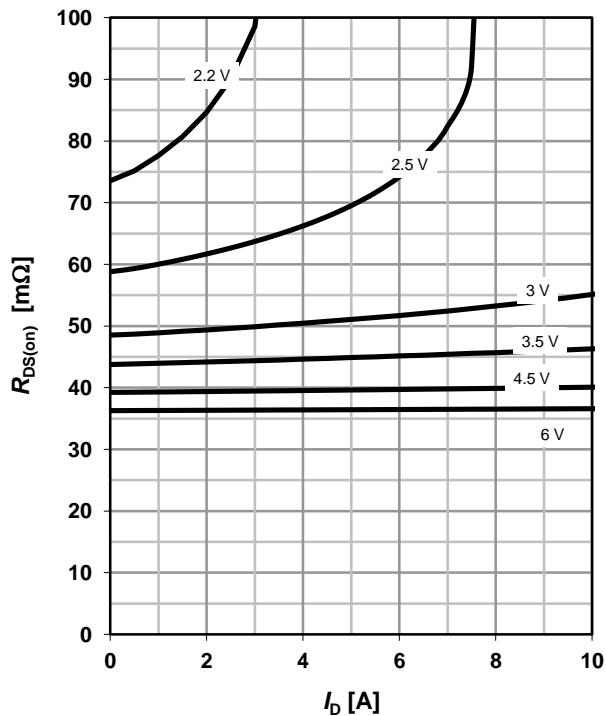
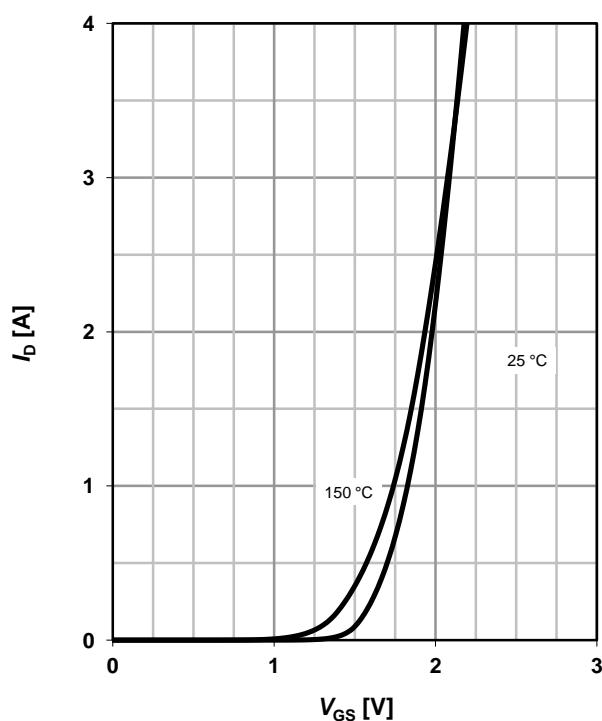
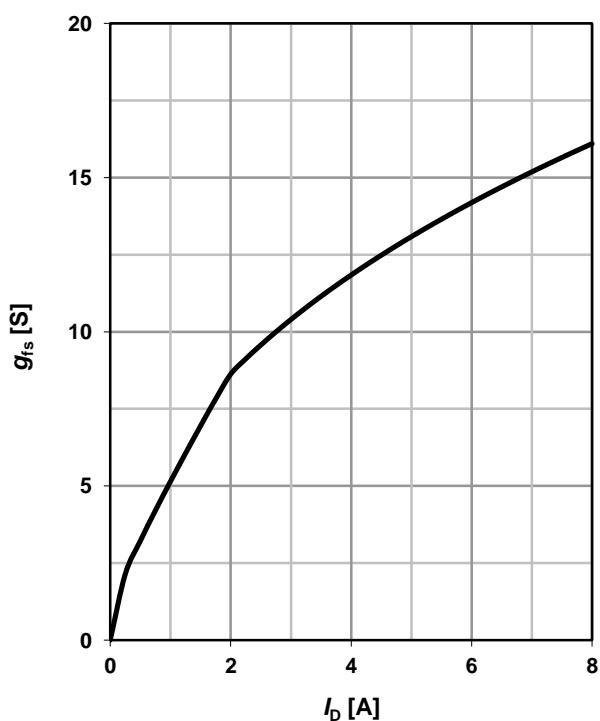
parameter: t_p

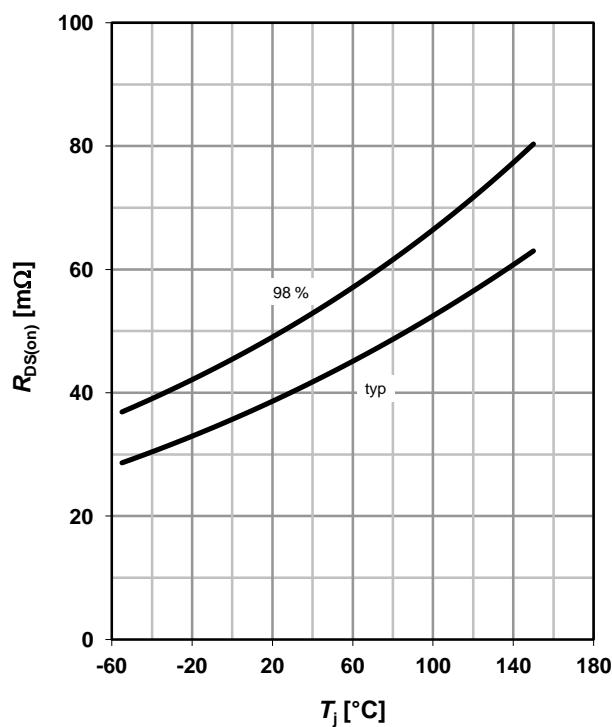

4 Max. transient thermal impedance

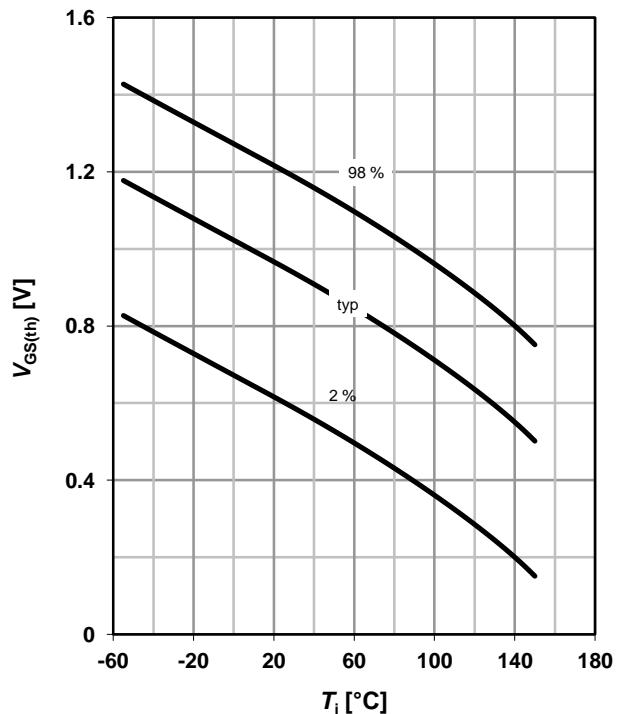
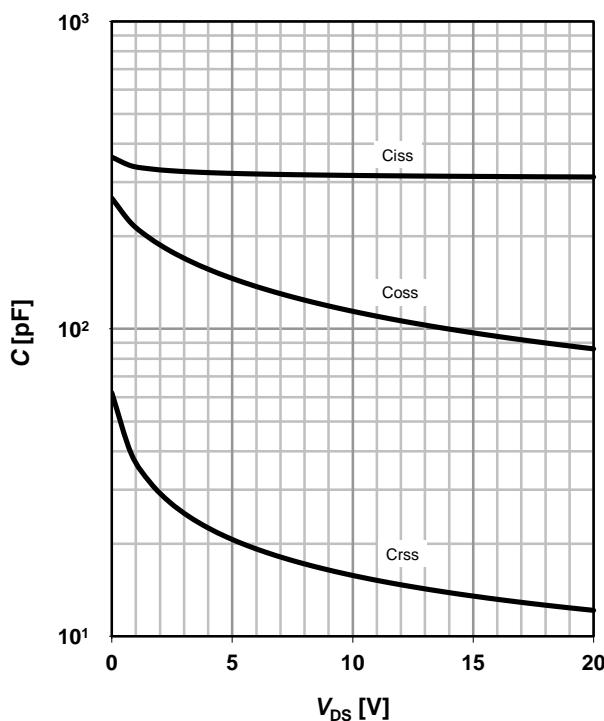
$$Z_{\text{thJA}} = f(t_p)$$

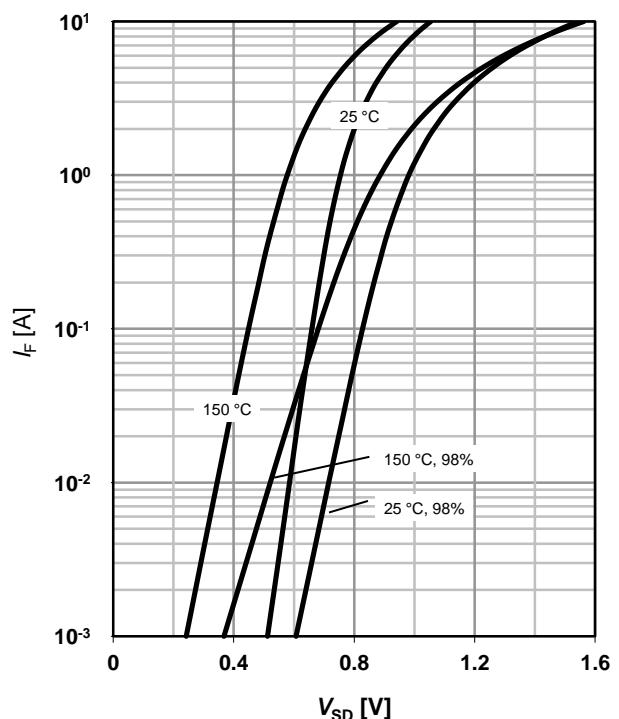
parameter: $D = t_p/T$



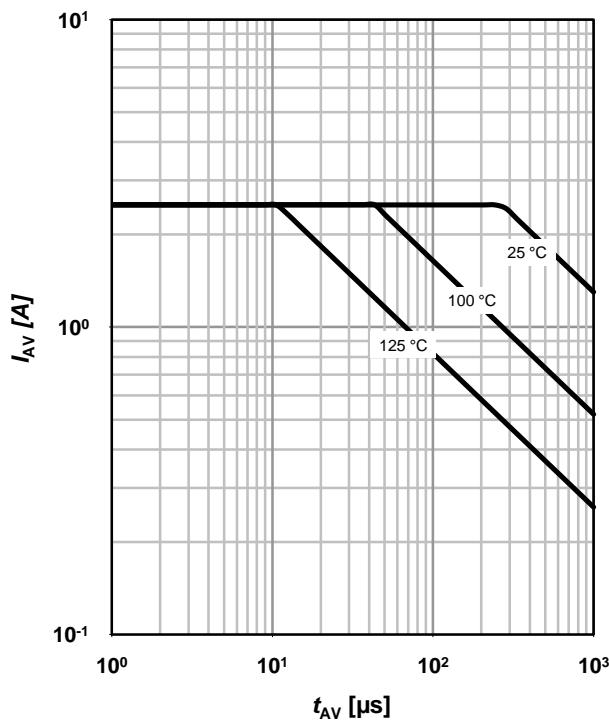
5 Typ. output characteristics
 $I_D=f(V_{DS})$; $T_j=25\text{ }^\circ\text{C}$
parameter: V_{GS} 
6 Typ. drain-source on resistance
 $R_{DS(on)}=f(I_D)$; $T_j=25\text{ }^\circ\text{C}$
parameter: V_{GS} 
7 Typ. transfer characteristics
 $I_D=f(V_{GS})$; $|V_{DS}|>2|I_D|R_{DS(on)max}$

8 Typ. forward transconductance
 $g_{fs}=f(I_D)$; $T_j=25\text{ }^\circ\text{C}$


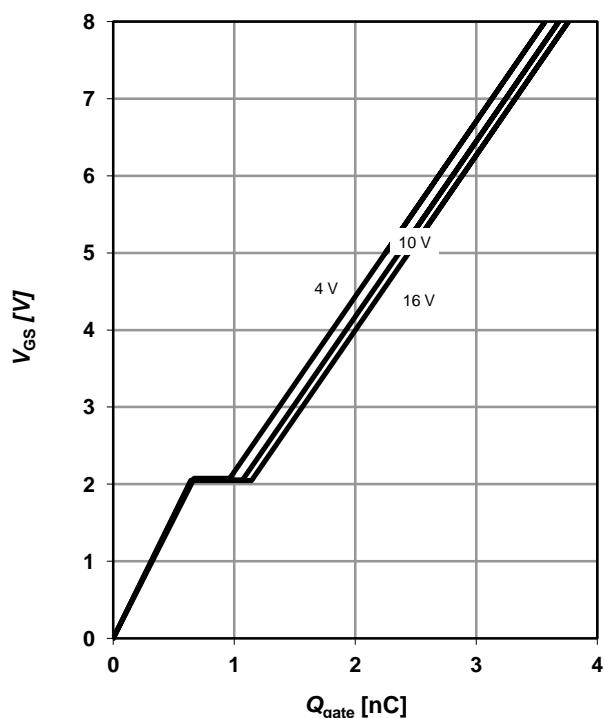
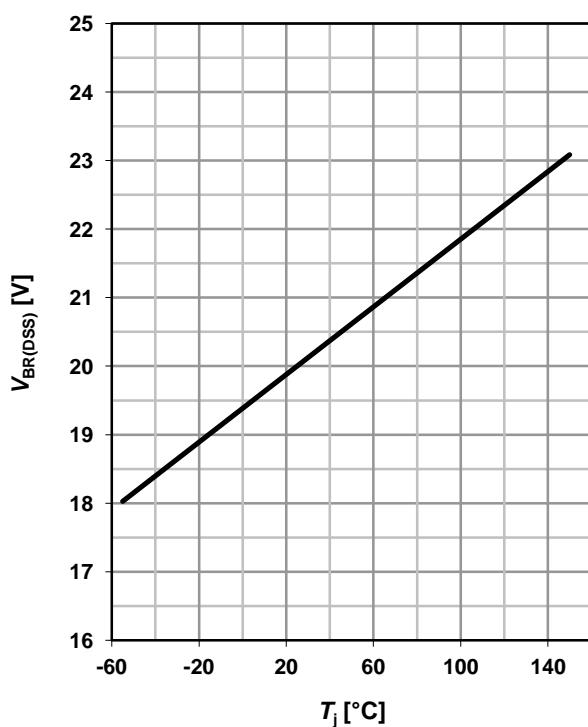
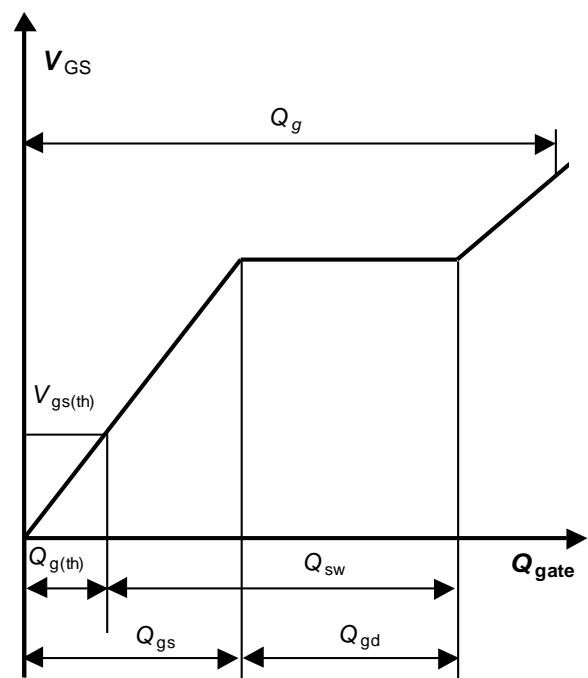
9 Drain-source on-state resistance
 $R_{DS(on)} = f(T_j); I_D = 2.5 \text{ A}; V_{GS} = 4.5 \text{ V}$

10 Typ. gate threshold voltage
 $V_{GS(th)} = f(T_j); V_{DS} = V_{GS}; I_D = 11 \mu\text{A}$

 parameter: I_D

11 Typ. capacitances
 $C = f(V_{DS}); V_{GS} = 0 \text{ V}; f = 1 \text{ MHz}; T_j = 25^\circ\text{C}$

12 Forward characteristics of reverse diode
 $I_F = f(V_{SD})$

 parameter: T_j


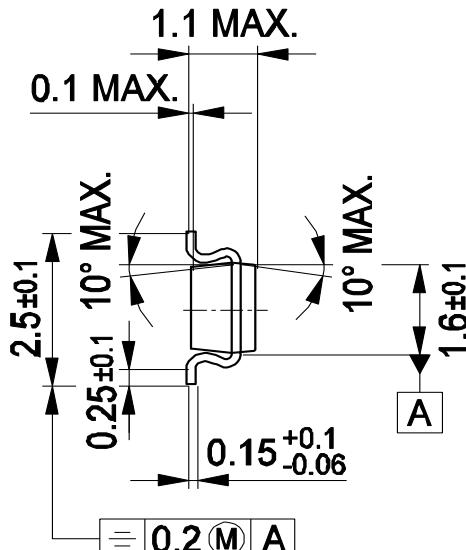
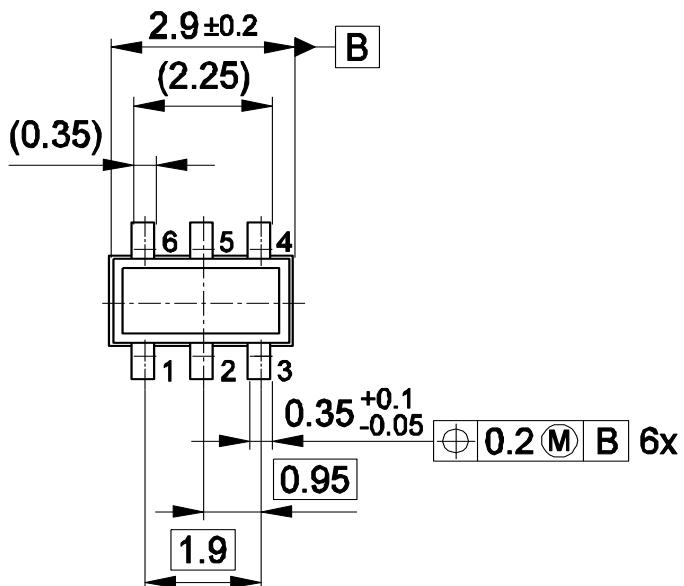
13 Avalanche characteristics
 $I_{AV}=f(t_{AV})$; $R_{GS}=25 \Omega$

parameter: $T_{j(\text{start})}$

14 Typ. gate charge
 $V_{GS}=f(Q_{\text{gate}})$; $I_D=2.5 \text{ A pulsed}$

parameter: V_{DD}

15 Drain-source breakdown voltage
 $V_{BR(DSS)}=f(T_j)$; $I_D=250 \mu\text{A}$

16 Gate charge waveforms


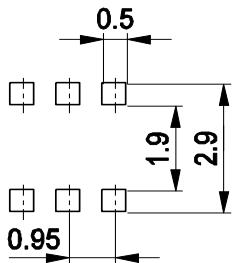
Package Outline:

TSOP6



GPX09300

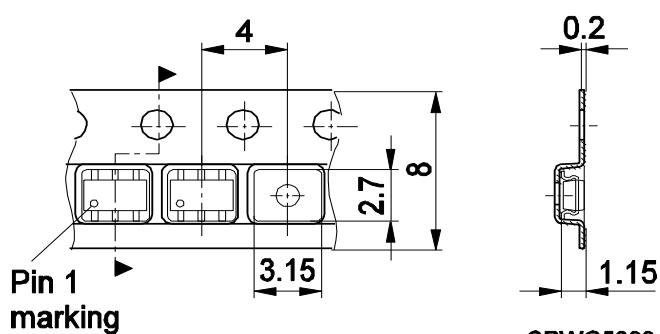
Footprint:



Remark: Wave soldering possible dep.
on customers process conditions

HLG09283

Packaging:



CPWG5899

Dimensions in mm

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